

Whereas the APGENCO Limited has been approached for evolving scheme for affording facilities for such internship training

Whereas the APGENCO limited has agreed to permit to work in establishment on the terms and conditions, here in after mentioned and subject to giving to this undertaking. I hereby agree and declare as follows.

- 2. I am not entitled for payment any wages or honorarium of any kind or seek employment on basis of the said internship.
- 3. I shall abide by the conditions set out in memo No.CE/O&M/ LS/AS/JAO/ (A) /C1F.128/D /2022, Dt.21-09-2022. No.
- 4. If any loss or damage is caused to the APGENCO limited during the period of Project Work by me, I under take to reimburse the same.
- 5. I will follow scrupulously the safety measure imposed by the establishment during my Project Work and never implicate the establishment for my negligence or for my inadvertences.
- 6. My parents also hereby agree to make good the loss if any caused to the establishment due to my negligence.
- 7. Myself and my parent undertake not to claim any damages or compensation either from the Engineering College or technical education department concerned industry Organization Corporation in case I/my son/my daughter/my ward sustain any injury or involve in any untoward or unexpected mishap during the course of study/Project Work.

[Signature of the Parent]

Signature of the Witness with Addresses

1. K. Shakuuthala 2. Aurt

k, Anusha Signature of the Student Name in block letters

K. ANUSHA

1CAD anily Signature of the Principal Principal

Government Degree College

CHINTURU



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MUKGAY Y.CH. VENKATA LAKSHM

Licensed Stamp Vendor

MODELLE No.04-28-041-2020

MANAHENDRAVARAM-53310

20 Ward, Cell: 8341403113

BOND OF UNDERTAKING

This bond of undertaking executed on the day. 21-19-1-2029. of September 2022 by M. Chinna Babu student of Govt Degree college in favour of the ANDHRA PRADESH GENERATION CORPORATION LIMITED here after called "APGENCO".

Whereas the students of M. Chinna Babu. Year 3rd Jean are required to undergo practical Training as part of their studies.

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[Signature of the Parent]

Signature of the Witness with Addresses

1. K. Shakunthala 2. April

Signature of the Student

Name in block letters

M. CHINNA BABU



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ల్ల్ 9 రెం ద్రమ్స [Signature of the Parent]

Signature of the Witness with Addresses

1. K. Shakurthala

2 Auf

Signature of the Student
Name in block letters
PULI SINGARAJU

Signature of the Principal



Whereas the students of S. Laulanga. Year ... Year are required to undergo practical Training as part of their studies.

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K. Mayou and [Signature of the Parent]

Signature of the Witness with Addresses

1. K. Shakuuthala 2 Aug

5. Lavanya.
Signature of the Student Name in block letters S-LAVANYA.



မေဝန်ပုံစိန် आंध्र प्रदेश ANDHRA PRADESH 7205 at 21/09/2022 Sode Susmitte D/O Ramudy Sode Susmitte D/O Ramudy

76AA 620392
Y.CH.VENKATA LAKSHMI
Licensed Stamp Vendor
L.No.04-28-041-2020
RAJAMAHENDRAVARAM-533101

## BOND OF UNDERTAKING

Whereas the students of S. Susmitha. Year 3rd year are required to undergo practical Training as part of their studies.

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[Signature of the Parent]

Signature of the Witness with Addresses

1. K. Shalawthala

S. Summera

Signature of the Student Name in block letters

S SULMITHA



Whereas the students of S. Noga Laxui Year ... 3 dear ... are required to undergo practical Training as part of their studies.

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はのひのかのかり [Signature of the Parent]

Signature of the Witness with Addresses

1. K. Shekurthola.

S. Nagalozmí Signature of the Student Name in block letters

S. NAGALAXMI

Signature of the Principal